

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.501296**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004001	1000000	7981.30664062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000223	1000000	444.84664917		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.089088	580000	177715.234375		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.064512	420000	128690.34375		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>306405.59375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24756.3964844		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24756.3964844</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2449.64892578		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2449.64892578</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001102	750000	2198.30053711		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000367	250000	732.101928711		
<b>Die Attach Total:</b>				<b>0.001469</b>	<b>1000000</b>	<b>2930.40258789</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.044291	135000	88352.9296875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.282148	860000	562836.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.001640	5000	3271.51806641		
		<b>Encapsulation Total:</b>				<b>0.328079</b>	<b>1000000</b>	<b>654461.125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	570.520812988		
					<b>TOTAL MASS (g) :</b>	<b>0.501296</b>		